

# **2017 18th International Conference on Electronic Packaging Technology (ICEPT 2017)**

**Harbin, China  
16-19 August 2017**

**Pages 1-568**



**IEEE Catalog Number: CFP17553-POD  
ISBN: 978-1-5386-2973-4**

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|-------------------------|-------------------|
| IEEE Catalog Number:    | CFP17553-POD      |
| ISBN (Print-On-Demand): | 978-1-5386-2973-4 |
| ISBN (Online):          | 978-1-5386-2972-7 |

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